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PATENTS
112055-0040

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re The Application of:
David Chong et al.

Serial No.: 09/823,600

Filed: March 30, 2001

For: PACKAGING SYSTEM FOR
DIE-UP CONNECTION OF A
DIE-DOWN ORIENTED INTE-
GRATED CIRCUIT

Examiner: Not yet assigned

Art Unit: Not yet assigned

Cesari and McKenna, LLP
88 Black Falcon Avenue
Boston, MA 02210

Honorable Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

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STATEMENT UNDER 37 CFR 3.73(b)

Fairchild Semiconductor Corporation, a corporation, states that it is the assignee of the entire right, title, and interest in the patent application identified above by virtue of an assignment of which a copy is attached.

The undersigned (whose title is supplied below) is authorized to act on behalf of the assignee.

4/26/02
Date

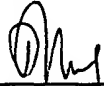
Paul D. Delva
Assistant Corporate Counsel

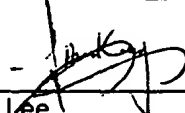
ASSIGNMENT

For good and valuable consideration, of which we acknowledge receipt, we, David Chong, H.K. Lee, Howard Allen and Stephen Martin of Penang and Penang, Malaysia, and Limington and South Portland, respectively, hereby sell, assign and transfer to Fairchild Semiconductor Corporation, a Delaware corporation having an address at 82 Running Hill Road, South Portland, Maine, its successors and assigns, the entire right title and interest throughout the world in our invention entitled **Packaging System for Die-Up Connection of a Die-Down Oriented Integrated Circuit** as described in the application for United States Patent Office which was filed on March 30, 2001, and assigned Serial No. 09/823,600, and any and all patent applications and patents of every country for said invention, including divisions, reissues, continuations and extensions thereof, and all rights of priority resulting from the filing of said applications.

We authorize the above-named assignee to apply for patents of foreign countries for said invention and to claim all rights of priority without further authorization from us; we agree to execute all papers useful in connection with said United States and foreign applications, and generally to do everything possible to aid said assignee, its successors, assigns and nominees, at their request and expense, in obtaining and enforcing patents for said invention in all countries; and we request any official whose duty it is to issue patents, to issue any and all patents granted for said invention to the above-named assignee, its successors and assigns.

Executed this 23 day of April, 2001


 David Chong
 Printed Name: DAVID CHONG SUOK LIM


 H.K. Lee
 Printed Name: LEE HUN KWANG.

 Howard Allen
 Printed Name: _____

 Stephen Martin
 Printed Name: _____

ASSIGNMENT

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Executed this 18 day of April, 2001

David Chong
Printed Name: _____

H.K. Lee
Printed Name: _____

Howard Allen
Howard Allen
Printed Name: Howard Allen

Stephen A Martin
Stephen Martin
Printed Name: Stephen A Martin